



FCP22N60N / FCPF22N60NT

N-Channel MOSFET

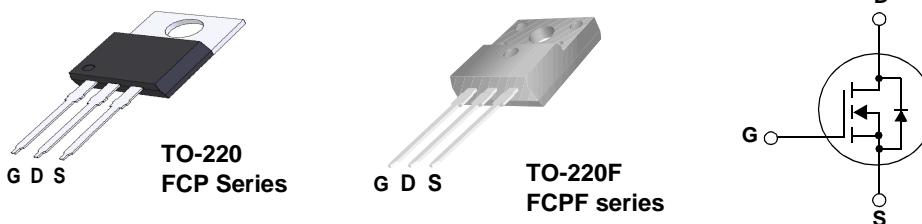
600V, 22A, 0.165Ω

Features

- $R_{DS(on)} = 0.140\Omega$ (Typ.) @ $V_{GS} = 10V$, $I_D = 11A$
- $BV_{DSS} > 650V$ @ $T_J = 150^\circ C$
- Ultra Low Gate Charge (Typ. $Q_g = 45nC$)
- Low Effective Output Capacitance
- 100% Avalanche Tested
- RoHS Compliant

Description

The SupreMOS MOSFET, Fairchild's next generation of high voltage super-junction MOSFETs, employs a deep trench filling process that differentiates it from preceding multi-epi based technologies. By utilizing this advanced technology and precise process control, SupreMOS provides world class Rsp, superior switching performance and ruggedness. This SupreMOS MOSFET fits the industry's AC-DC SMPS requirements for PFC, server/telecom power, FPD TV power, ATX power, and industrial power applications.



MOSFET Maximum Ratings $T_C = 25^\circ C$ unless otherwise noted*

Symbol	Parameter		FCP22N60N	FCPF22N60NT	Units
V_{DSS}	Drain to Source Voltage		600		V
V_{GSS}	Gate to Source Voltage		± 30		V
I_D	Drain Current	Continuous ($T_C = 25^\circ C$)	22	22*	A
		Continuous ($T_C = 100^\circ C$)	13.8	13.8*	
I_{DM}	Drain Current	Pulsed (Note 1)	66	66*	A
E_{AS}	Single Pulsed Avalanche Energy (Note 2)		672		mJ
I_{AR}	Avalanche Current		7.3		A
E_{AR}	Repetitive Avalanche Energy		2.75		mJ
dv/dt	Peak Diode Recovery dv/dt (Note 3)		20		V/ns
	MOSFET dv/dt		100		
P_D	Power Dissipation	($T_C = 25^\circ C$)	205	39	W
		Derate above $25^\circ C$	1.64	0.31	$W/\text{ }^\circ C$
T_J, T_{STG}	Operating and Storage Temperature Range		-55 to $+150$		$^\circ C$
T_L	Maximum Lead Temperature for Soldering Purpose, 1/8" from Case for 5 Seconds		300		$^\circ C$

*Drain current limited by maximum junction temperature

Thermal Characteristics

Symbol	Parameter	FCP22N60N	FCPF22N60NT	Units
$R_{\theta JC}$	Thermal Resistance, Junction to Case	0.61	3.2	$^\circ C/W$
$R_{\theta JS}$	Thermal Resistance, Case to Heat Sink (Typical)	0.5	0.5	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	62.5	62.5	

Package Marking and Ordering Information $T_C = 25^\circ\text{C}$ unless otherwise noted

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FCP22N60N	FCP22N60N	TO-220	-	-	50
FCPF22N60NT	FCPF22N60NT	TO-220F	-	-	50

Electrical Characteristics

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
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Off Characteristics

BV_{DSS}	Drain to Source Breakdown Voltage	$I_D = 1\text{mA}, V_{GS} = 0\text{V}, T_J = 25^\circ\text{C}$	600	-	-	V
		$I_D = 1\text{mA}, V_{GS} = 0\text{V}, T_J = 150^\circ\text{C}$	650	-	-	
$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	Breakdown Voltage Temperature Coefficient	$I_D = 1\text{mA}$, Referenced to 25°C	-	0.68	-	$^\circ\text{C}$
		$V_{DS} = 480\text{V}, V_{GS} = 0\text{V}$	-	-	10	
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 480\text{V}, T_J = 125^\circ\text{C}$	-	-	100	μA
		$V_{GS} = \pm 50\text{V}, V_{DS} = 0\text{V}$	-	-	± 100	
I_{GSS}	Gate to Body Leakage Current	$V_{GS} = \pm 50\text{V}, V_{DS} = 0\text{V}$	-	-	-	nA

On Characteristics

$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_D = 250\mu\text{A}$	2.0	3	4.0	V
$R_{DS(\text{on})}$	Static Drain to Source On Resistance	$V_{GS} = 10\text{V}, I_D = 11\text{A}$	-	0.140	0.165	Ω
g_{FS}	Forward Transconductance	$V_{DS} = 20\text{V}, I_D = 11\text{A}$	-	22	-	S

Dynamic Characteristics

C_{iss}	Input Capacitance	$V_{DS} = 100\text{V}, V_{GS} = 0\text{V}$ $f = 1\text{MHz}$	-	1950	-	pF
C_{oss}	Output Capacitance		-	75.9	-	pF
C_{rss}	Reverse Transfer Capacitance		-	3	-	pF
C_{oss}	Output Capacitance	$V_{DS} = 380\text{V}, V_{GS} = 0\text{V}, f = 1\text{MHz}$	-	43.2	-	pF
$C_{\text{oss eff}}$	Effective Output Capacitance	$V_{DS} = 0\text{V}$ to $480\text{V}, V_{GS} = 0\text{V}$	-	196.4	-	pF
$Q_{\text{g(tot)}}$	Total Gate Charge at 10V		-	45	-	nC
Q_{gs}	Gate to Source Gate Charge	$V_{DS} = 380\text{V}, I_D = 11\text{A}, V_{GS} = 10\text{V}$ (Note 4)	-	8.7	-	nC
Q_{gd}	Gate to Drain "Miller" Charge		-	14.5	-	nC
ESR	Equivalent Series Resistance (G-S)	Drain Open, $f=1\text{MHz}$	-	1	-	Ω

Switching Characteristics

$t_{\text{d(on)}}$	Turn-On Delay Time	$V_{DD} = 380\text{V}, I_D = 11\text{A}$ $R_G = 4.7\Omega$	-	16.9	-	ns
	Turn-On Rise Time		-	16.7	-	ns
	Turn-Off Delay Time		-	49	-	ns
	Turn-Off Fall Time		-	4	-	ns

Drain-Source Diode Characteristics

I_S	Maximum Continuous Drain to Source Diode Forward Current	-	-	22	A
I_{SM}	Maximum Pulsed Drain to Source Diode Forward Current	-	-	66	A
V_{SD}	Drain to Source Diode Forward Voltage	$V_{GS} = 0\text{V}, I_{SD} = 11\text{A}$	-	-	1.2
t_{rr}	Reverse Recovery Time	$V_{GS} = 0\text{V}, I_{SD} = 11\text{A}$	-	350	-
Q_{rr}	Reverse Recovery Charge	$dI_F/dt = 100\text{A}/\mu\text{s}$	-	6	μC

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature
2. $I_{AS} = 7.3\text{A}$, $R_G = 25\Omega$, Starting $T_J = 25^\circ\text{C}$
3. $I_{SD} \leq 22\text{A}$, $di/dt \leq 200\text{A}/\mu\text{s}$, $V_{DD} \leq 380\text{V}$, Starting $T_J = 25^\circ\text{C}$
4. Essentially Independent of Operating Temperature Typical Characteristics

Typical Performance Characteristics

Figure 1. On-Region Characteristics

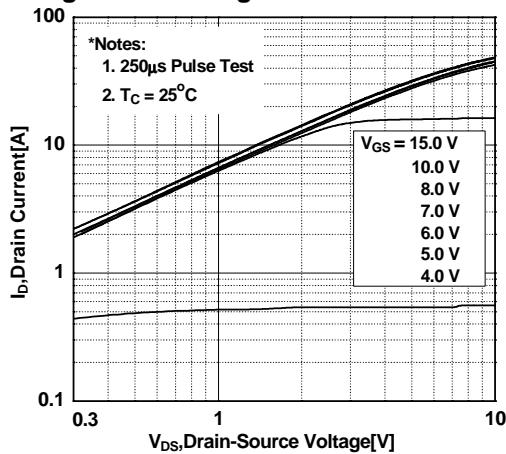


Figure 2. Transfer Characteristics

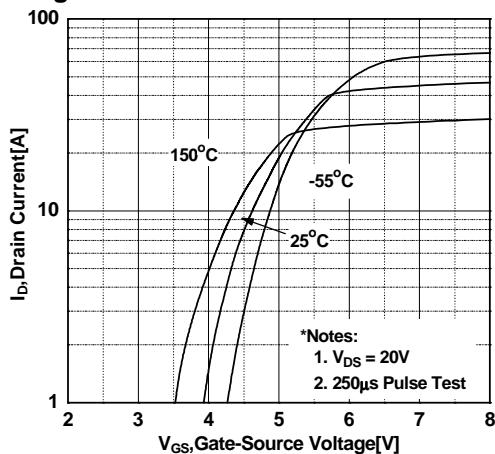


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

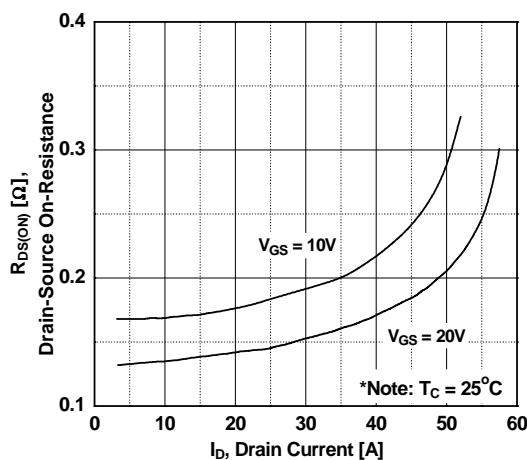


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

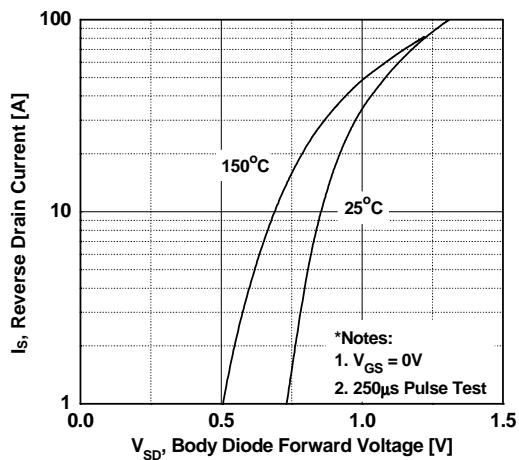


Figure 5. Capacitance Characteristics

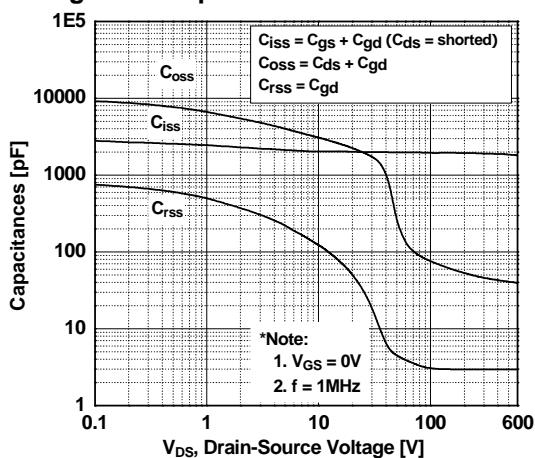


Figure 6. Gate Charge Characteristics

